



## Advances in Additive Manufacturing: Horizons of Novel Processes and Applications

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### Message from the Guest Editor

Additive manufacturing (AM) is highly attractive to scientists, as well as to mechanical, materials, chemical, and biomedical engineers and technologists, and it involves not only different important issues of physics and chemistry, but also machinery, software, machine learning, process organization, control, optimization and repeatability, economics, materials characterization, failure analysis and quality assurance, etc. The main reason for its popularity is the unique possibility of combining AM with different 3D printing technologies relevant to a wide spectrum of materials (metals, ceramics, composites, polymers, organics, etc.) with processes digitalization and artificial intelligence.

This Special Issue provides a forum for researchers, engineers, and practitioners to report their latest achievements and to highlight critical issues and challenges for future investigations of the design and applications of 3D printing and additive manufacturing.





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## Editor-in-Chief

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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